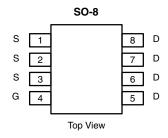




Vishay Siliconix

N-Channel 100 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | |
|---------------------|-----------------------------------|---------------------------------|-----------------------|--|--|--|
| V _{DS} (V) | $R_{DS(on)}(\Omega)$ Max. | I _D (A) ^a | Q _g (Typ.) | | | |
| | 0.0100 at V _{GS} = 10 V | 19.7 | | | | |
| 100 | 0.0105 at V _{GS} = 7.5 V | 19.2 | 27.9 nC | | | |
| | 0.0120 at V _{GS} = 6.0 V | 18 | | | | |



Ordering Information: Si4090DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

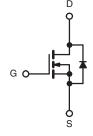
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested
- Material categorization: For definitions of compliance please see www.vishav.com/doc?99912



HALOGEN **FREE**

APPLICATIONS

- DC/DC Primary Side Switch
- Telecom/Server
- Motor Drive Control
- Synchronous Rectification



N-Channel MOSFET

| ABSOLUTE MAXIMUM RATIN | IGS (T _A = 25 °C | , unless oth | erwise noted) | |
|--|-----------------------------|-----------------------------------|----------------------|----|
| Parameter | Symbol | Limit | Unit | |
| Drain-Source Voltage | V_{DS} | 100 | V | |
| Gate-Source Voltage | | V_{GS} | ± 20 | v |
| | T _C = 25 °C | | 19.7 | |
| Continuous Drain Current /T 150 °C\ | T _C = 70 °C | | 15.8 | |
| Continuous Drain Current (T _J = 150 °C) | T _A = 25 °C | - I _D | 13.2 ^{b, c} | |
| | T _A = 70 °C | | 10.4 ^{b, c} | A |
| Pulsed Drain Current (t = 300 μs) | | I _{DM} | 70 | A |
| 0 11 0 0 1 | T _C = 25 °C | - I _S | 7 | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | | 3.1 ^{b, c} | |
| Single Pulse Avalanche Current | L = 0.1 mH | I _{AS} | 30 | |
| Avalanche Energy L = 0.1 mH | | E _{AS} | 45 | mJ |
| | T _C = 25 °C | P _D | 7.8 | |
| Maximum Power Dissipation | T _C = 70 °C | | 5 | w |
| Maximum Fower Dissipation | T _A = 25 °C | | 3.5 ^{b, c} | VV |
| | T _A = 70 °C | | 2.2 ^{b, c} | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | °C |

| THERMAL RESISTANCE RATINGS | | | | | | | |
|---|--------------|-------------------|---------|------|---------|--|--|
| Parameter | Symbol | Typical | Maximum | Unit | | | |
| Maximum Junction-to-Ambient ^{b, d} | t ≤ 10 s | R _{thJA} | 29 | 35 | °C/W | | |
| Maximum Junction-to-Foot (Drain) | Steady State | R _{thJF} | 13 | 16 | - °C/VV | | |

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 80 °C/W.

Si4090DY

Vishay Siliconix



| SPECIFICATIONS (T _J = 25 °C, unless otherwise noted) | | | | | | | |
|--|-------------------------|--|------|--------|--------|---------|--|
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 100 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | I _D = 250 μA | | 67 | | mV/°C | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | - 10 – 200 μπ | | - 6.4 | | liiv/ C | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_D = 250 \mu A$ | 2 | | 3.3 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 100 V, V _{GS} = 0 V V _{DS} = 100 V, V _{GS} = 0 V, T _J = 55 °C | | | 1 | μΑ | |
| Zero Gate Voltage Drain Gurrent | | | | | 10 | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$ | 30 | | | Α | |
| | | V _{GS} = 10 V, I _D = 15 A | | 0.0080 | 0.0100 | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = 7.5 V, I _D = 12 A | | 0.0085 | 0.0105 | _ | |
| | | $V_{GS} = 6.0 \text{ V}, I_D = 10 \text{ A}$ | | 0.0090 | 0.0120 | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 15 A | | 54 | | S | |
| Dynamic ^b | | | L | | | | |
| Input Capacitance | C _{iss} | | | 2410 | | | |
| Output Capacitance | C _{oss} | $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 790 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 60 | | | |
| · | 0 | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$ | | 45.6 | 69 | | |
| Total Gate Charge | Q_g | Q _g | | 27.9 | 42 | nC | |
| Gate-Source Charge | Q _{gs} | $V_{DS} = 50 \text{ V}, V_{GS} = 6 \text{ V}, I_{D} = 10 \text{ A}$ | | 8.5 | | | |
| Gate-Drain Charge | Q_{gd} | | | 9.2 | | | |
| Output Charge | Q _{oss} | V _{DS} = 50 V, V _{GS} = 0 V | | 63 | 95 | | |
| Gate Resistance | R_g | f = 1 MHz | 0.4 | 1.3 | 2.6 | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 16 | 32 | | |
| Rise Time | t _r | $V_{DD} = 50 \text{ V}, R_L = 5 \Omega$ | | 11 | 22 | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 10 \text{ A}, V_{GEN} = 7.5 \text{ V}, R_g = 1 \Omega$ | | 35 | 70 | | |
| Fall Time | t _f | | | 10 | 20 | | |
| Turn-On Delay Time | t _{d(on)} | | | 14 | 28 | ns | |
| Rise Time | t _r | $V_{DD} = 50 \text{ V}, R_L = 5 \Omega$ | | 10 | 20 | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ | | 36 | 70 | | |
| Fall Time | t _f | | | 10 | 20 | | |
| Drain-Source Body Diode Characteristi | cs | | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | | | 7 | | |
| Pulse Diode Forward Current ^a | I _{SM} | | | | 70 | Α | |
| Body Diode Voltage | V _{SD} | I _S = 5 A | | 0.75 | 1.1 | ٧ | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 49 | 95 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | 58 | 115 | nC | |
| Reverse Recovery Fall Time | t _a | $I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$ | | 21 | | ns | |
| Reverse Recovery Rise Time | t _b | 1 | | 28 | | | |

Notes:

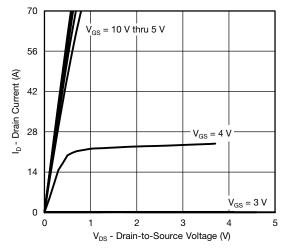
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

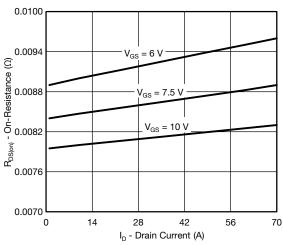


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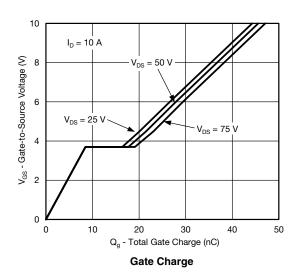
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

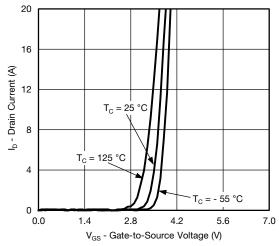


Output Characteristics

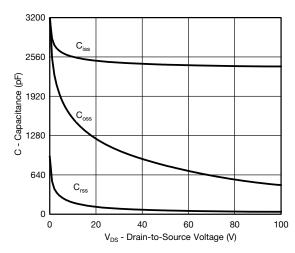


On-Resistance vs. Drain Current

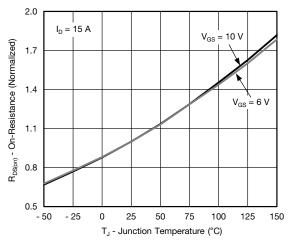




Transfer Characteristics



Capacitance

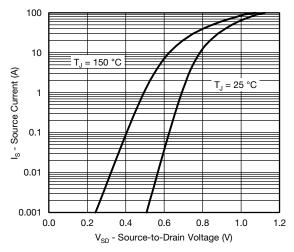


On-Resistance vs. Junction Temperature

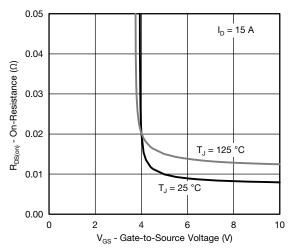
Si4090DY

Vishay Siliconix

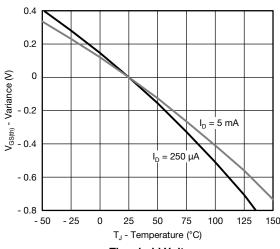
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



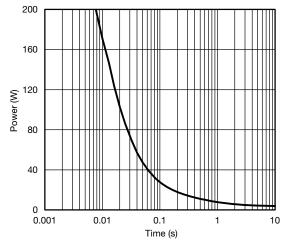
Source-Drain Diode Forward Voltage



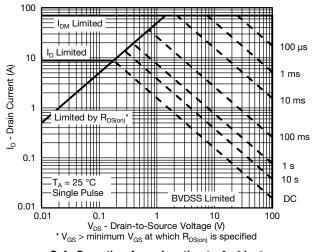
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

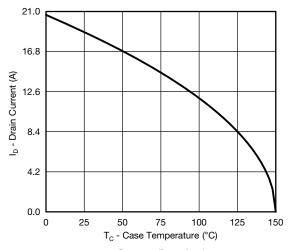


Safe Operating Area, Junction-to-Ambient

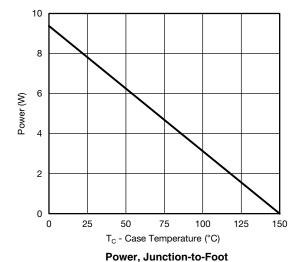


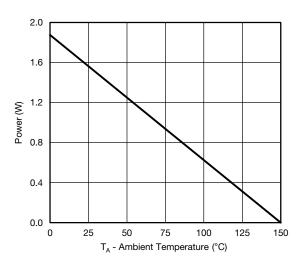
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*





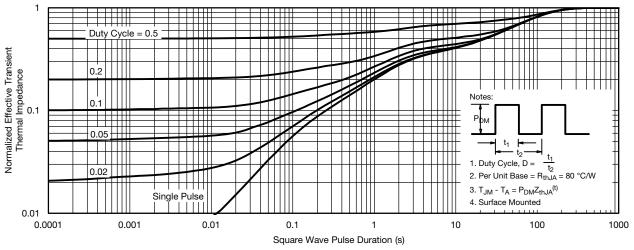
Power, Junction-to-Ambient

^{*} The power dissipation PD is based on TJ(max) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

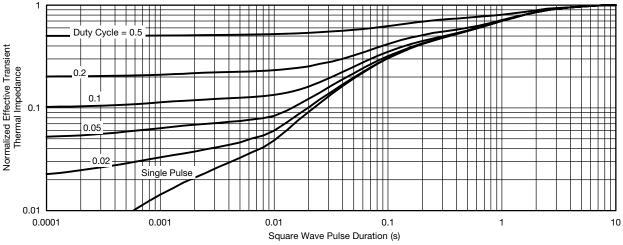
Si4090DY

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







| | MILLIM | IETERS | INC | INCHES | | |
|--------------------------------|--------|--------|--------|-----------|--|--|
| DIM | Min | Max | Min | Max | | |
| Α | 1.35 | 1.75 | 0.053 | 0.069 | | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | | |
| Е | 3.80 | 4.00 | 0.150 | 0.157 | | |
| е | 1.27 | BSC | 0.050 | 0.050 BSC | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | | |
| q | 0° | 8° | 0° | 8° | | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | | |
| ECN: C-06527-Rev. I. 11-Sep-06 | | | | | | |

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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